

12-20-00

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Atty. Docket No. AMAT/5614/CMP/CMP/RKK

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Box Patent Application
 Assistant Commissioner of Patents and Trademarks
 Washington, D.C. 20231

Re: Inventor(s): WEI-YUNG HSU, LIANG-YUH CHEN, RATSON MORAD, DANIEL A. CARL
 and SASSON SOMEKH
 Title: INTEGRATED MULTI-STEP GAP FILL AND ALL FEATURE PLANARIZATION FOR
 CONDUCTIVE MATERIALS

JC966 U.S. PTO
 09/139139
 12/18/00

Transmitted herewith is the patent application identified above, including:

- ☒ Specification, claims and abstract, totaling 36 pages.
- ☒ Drawings totaling 15 pages, ☒ Formal ☐ Informal.
- ☒ Executed Declaration and Power of Attorney.
- ☐ Information Disclosure Statement w/ Form 1449 and References.
- ☒ Assignment of the invention to **Applied Materials, Inc.**
- ☒ Assignment Recordation Cover Sheet

FEE CALCULATION					
Fee Items	Claims Filed	Included With Basic Fee	Extra Claims	Fee Rate	Total
Total Claims	88	-20=	68	x \$18.00	\$1224.00
Independent Claims	6	-3=	3	x \$80.00	\$ 240.00
Basic Filing Fee				\$710.00	\$ 710.00
TOTAL FEES					\$2174.00

- ☒ The Commissioner is hereby authorized to charge **\$2174.00** to Deposit Account No. **50-1074/5614/CMP/CMP/RKK**.
- ☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. **50-1074/5614/CMP/CMP/RKK**. A duplicate copy of this transmittal is enclosed.
- ☒ Please address all future correspondence to:

**PATENT COUNSEL
 APPLIED MATERIALS, INC.
 Legal Affairs Department
 P.O.BOX 450A
 Santa Clara, CA. 95052**

I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231

Express Mail Receipt No. EL684621317US

Date of Deposit 12-18-2000

Signature Robert W. Mulcahy

Respectfully submitted,

Robert W. Mulcahy
 Registration No. 25,436